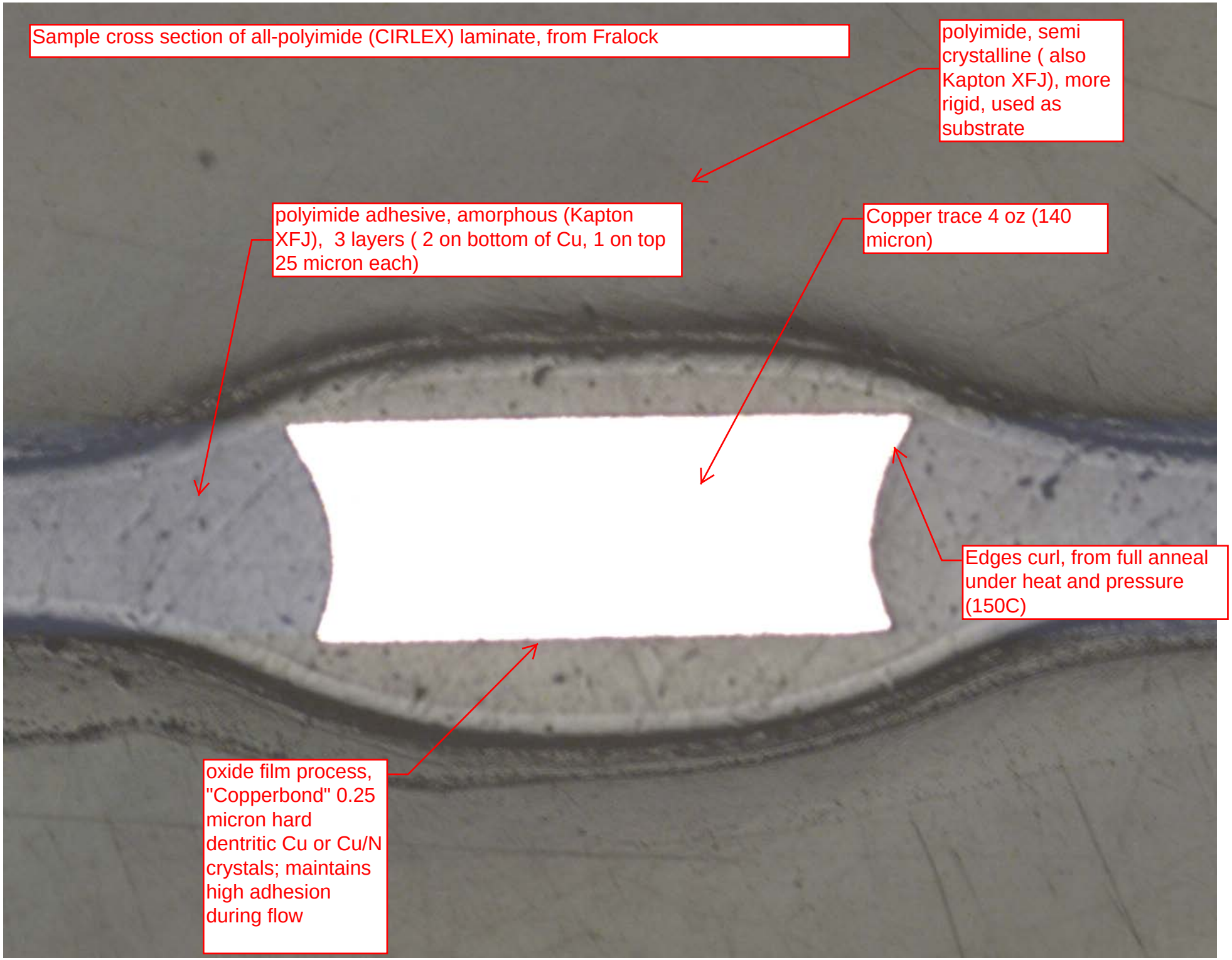
Sample cross section of all-polyimide (CIRLEX) laminate, from Fralock
polyimide, semi crystalline (also Kapton XFJ), more rigid, used as substrate
polyimide adhesive, amorphous (Kapton XFJ), 3 layers (2 on bottom of Cu, 1 on top 25 micron each)
Copper trace 4 oz (140 micron)
Edges curl, from full anneal under heat and pressure (150C)
oxide film process, "Copperbond" 0.25 micron hard dentritic Cu or Cu/N crystals; maintains high adhesion during flow

(JPEG Image, 1280x1024 pixels)